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(54) **METHOD OF DIRECTLY PATTERNING  
STRETCHABLE SUBSTRATE AND  
STRETCHABLE ELECTRODE FABRICATED  
BY THE SAME**

(52) **U.S. Cl.**

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**ABSTRACT**

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Disclosed are a method of directly patterning a stretchable substrate; and a stretchable electrode fabricated by the method. More particularly, the method of directly patterning a stretchable substrate includes: forming a hydrophilic group on a surface of a stretchable substrate by UV-ozone treatment; forming at least one layer to be etched on the hydrophilic group-formed stretchable substrate, wherein the at least one layer to be etched includes an adhesion enhancing material; forming a photoresist layer on the at least one layer to be etched; exposing the photoresist layer; and patterning the at least one layer to be etched using the exposed photoresist layer, wherein a carbon chain included in the adhesion enhancing material forms ether bonding (R—O—R) with a hydrophilic group formed on the surface of the stretchable substrate.

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